

# 8331



## Silver Conductive Epoxy Adhesive

8331 is an electrically conductive, silver-filled 2-part epoxy adhesive. It is smooth, non-sagging, thixotropic, and bonds well to a wide variety of substrates.

This product allows for quick, cold-soldering repairs. It can also be used as a solder replacement for bonding heat-sensitive electronic components, or for making conductive connections where soldering is not an option, such as when bonding to glass, soft metals, or plastics.

8331 has been formulated to be economical. For a higher fill that maximizes conductivity, use 8330. For a longer working time, use 8331S.



## Features and Benefits

- Creates strong permanent electrical connections
- Cures at room temperature
- Excellent adhesion to many substrates
- Room temperature storage
- Long shelf life

## Available Packaging

Cat. No.	Packaging	Net Vol.	Net Wt.
8331-14G	2 Syringe kit	6 mL	14.4 g
8331-50ML	2 Jar kit	50 mL	120 g
8331-200ML	2 Can kit	200 mL	482 g

## Contact Information

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## Cured Properties

Resistivity	$7.0 \times 10^{-3} \Omega\text{-cm}$
Hardness	73 D
Tensile Strength	13 N/mm <sup>2</sup>
Compressive Strength	39 N/mm <sup>2</sup>
Lap Shear (stainless steel)	3.8 N/mm <sup>2</sup>
(aluminum)	5.5 N/mm <sup>2</sup>
Water Absorption	0.04 %
Outgassing @ 125 °C for 24 h	6.3 %
Glass Transition Temperature (T <sub>g</sub> )	50 °C
CTE Prior T <sub>g</sub>	54 ppm/°C
CTE After T <sub>g</sub>	169 ppm/°C
Thermal Conductivity @ 25 °C	1.4 W/(m·K)
Service Temperature Range	-55–150 °C

## Usage Parameters

Working Time	10 min
Service Cure	5 h @ 22 °C
Mix Ratio by Volume	1:1
Mix Ratio by Weight	1.2:1

## Uncured Properties

Mixed Density	2.29 g/mL
Shelf Life	3 y
Viscosity @ 25 °C	(A) 1 000 Pa·s (B) 15 000 Pa·s

## Application Instructions

Read the product SDS before using this product (downloadable at [www.mgchemicals.com](http://www.mgchemicals.com)).

## Recommended Preparation

Clean the substrate with Isopropyl Alcohol, MG #824, so the surface is free of oils, dust, and other residues.

## Syringe

1. Twist and remove the cap from the syringe. Do not discard cap.
2. Measure 1 part by volume of A.
3. Measure 1 part by volume of B.
4. Dispense material on a mixing surface or container, and thoroughly mix parts A and B together.
5. To stop the flow, pull back on the plunger.
6. Clean nozzle to prevent contamination and material buildup.
7. Replace the cap on the syringe.

## Can or Jar

1. Stir each part individually to re-incorporate material that may have separated.
2. Measure 1.2 part by weight of A.
3. Measure 1 part by weight of B.
4. Thoroughly mix parts A and B together.
5. Apply adhesive to the application area.

## Cure Instructions

Allow to cure at room temperature for 24 hours, or cure the adhesive in an oven at one of these time/temperature options:

- 15 min @ 65 °C
- 7 min @ 125 °C

## Storage and Handling

Store between 16 and 27 °C in a dry area, away from sunlight (see SDS). To maximize shelf life, recap product firmly when not in use.

## Disclaimer

This information is believed to be accurate. It is intended for professional end-users who have the skills required to evaluate and use the data properly. M.G. Chemicals Ltd. does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.